

MJ N-Channel Enhancement Mode Power MOSFET

Description

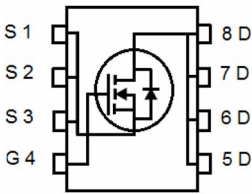
The MJ8060CG uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- ◆ $V_{DS}=80V, I_D=60A$
 $R_{DS(ON)}=9m\Omega$ (typical) @ $V_{GS}=10V$
- ◆ High density cell design for ultra low R_{dson}
- ◆ Very low on-resistance $R_{DS(on)}$
- ◆ Good stability and uniformity with high E_{AS}
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating

Application

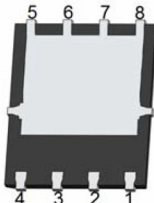
- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification



Schematic Diagram



Top View



Bottom View

100% UIS TESTED! 100% ΔV_{ds} TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ8060CG	MJ8060CG	DFN 5x6-8L	-	-	-

Absolute Maximum Ratings ($T_A=25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	80	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	60	A
Drain Current-Continuous($T_C=100^{\circ}\text{C}$)	$I_{D(100^{\circ}\text{C})}$	42.4	A
Pulsed Drain Current	I_{DM}	240	A
Maximum Power Dissipation	P_D	85	W
Single pulse avalanche energy ^(Note 5)	E_{AS}	380	mJ
Derating factor		0.68	W/ $^{\circ}\text{C}$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^{\circ}\text{C}$

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta JC}$	1.5	$^{\circ}\text{C/W}$
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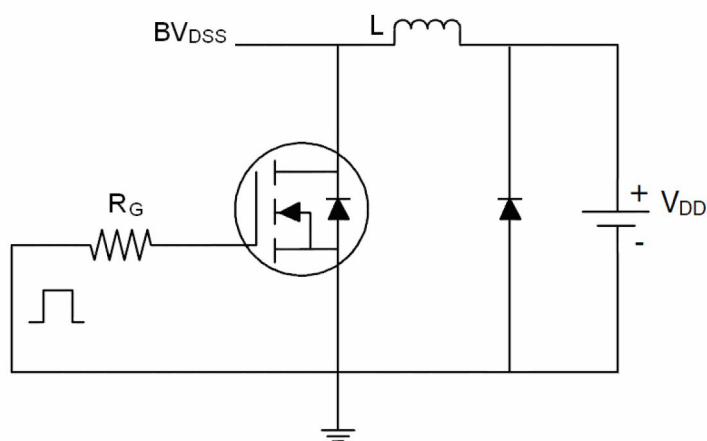
Electrical Characteristics (T_A =25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	80	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics <small>(Note 3)</small>						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	2	3	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	9	12	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =20A	-	30	-	S
Dynamic Characteristics <small>(Note 4)</small>						
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V, F=1.0MHz	-	4414	-	PF
Output Capacitance	C _{oss}		-	219	-	PF
Reverse Transfer Capacitance	C _{rss}		-	188	-	PF
Switching Characteristics <small>(Note 4)</small>						
Turn-on Delay Time	t _{d(on)}	V _{DD} =40V,R _L =15Ω V _{GS} =10V,R _G =2.5Ω	-	19	-	nS
Turn-on Rise Time	t _r		-	12	-	nS
Turn-Off Delay Time	t _{d(off)}		-	40	-	nS
Turn-Off Fall Time	t _f		-	15	-	nS
Total Gate Charge	Q _g	V _{DS} =40V,I _D =20A, V _{GS} =10V	-	81.5	-	nC
Gate-Source Charge	Q _{gs}		-	26.9	-	nC
Gate-Drain Charge	Q _{gd}		-	23.7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <small>(Note 3)</small>	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current <small>(Note 2)</small>	I _S		-	-	60	A
Reverse Recovery Time	t _{rr}	T _J =25°C, I _F =20A di/dt=100A/μs <small>(Note 3)</small>	-	36	-	nS
Reverse Recovery Charge	Q _{rr}		-	54	-	nC

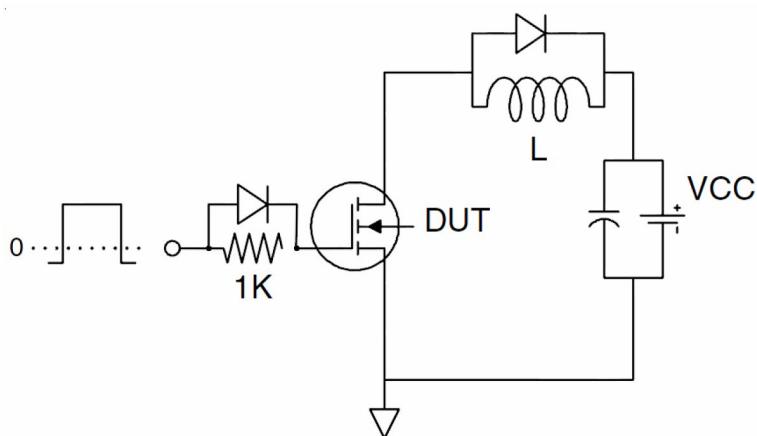
Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
② Surface Mounted on FR4 Board, t≤10sec.
③ Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.
④ Guaranteed by design, not subject to production
⑤ EAS condition: T_J=25℃, V_{DD}=40V,V_G=10V,L=0.5mH,R_g=25Ω

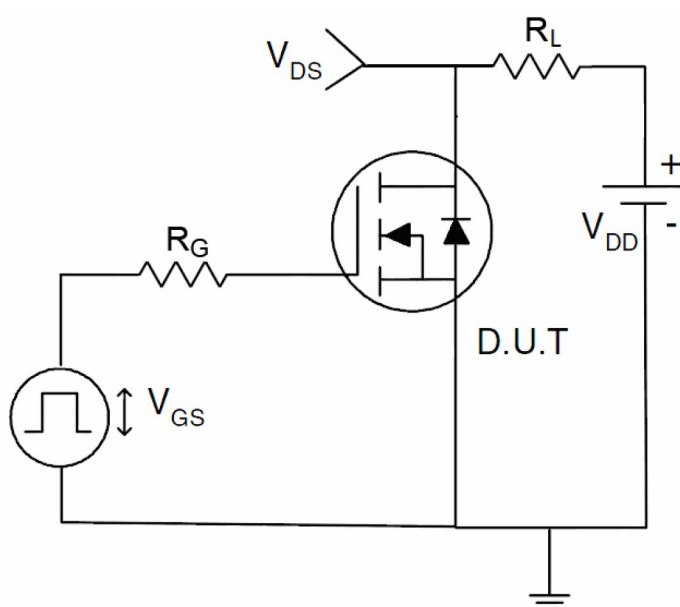
Test Circuit



EAS test Circuit

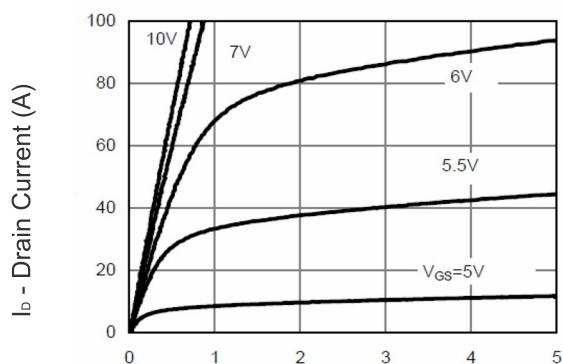


Gate charge test Circuit



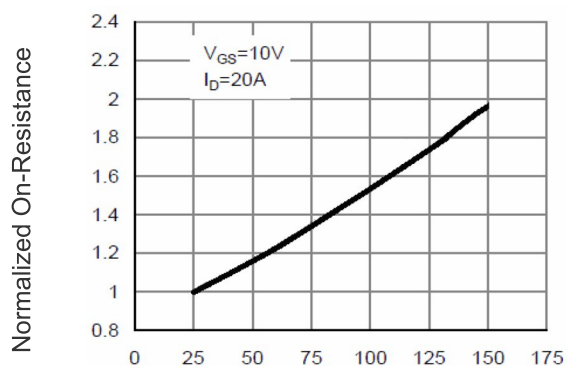
Switch Time Test Circuit

Typical Electrical and Thermal Characteristics (Curves)



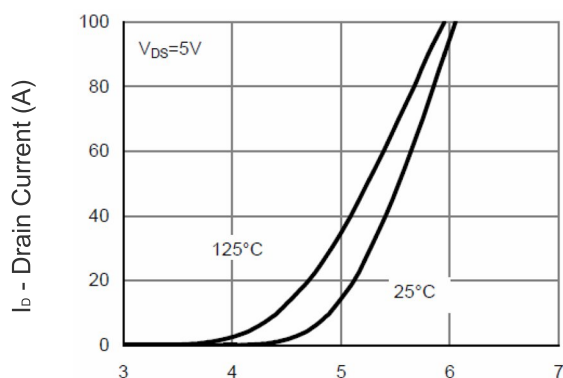
V_{DS} Drain-Source Voltage (V)

Figure 1 Output Characteristics



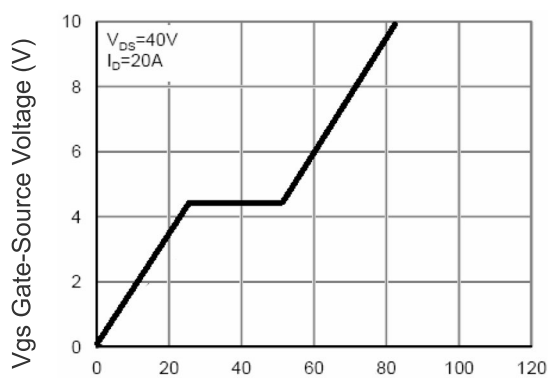
T_J -Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



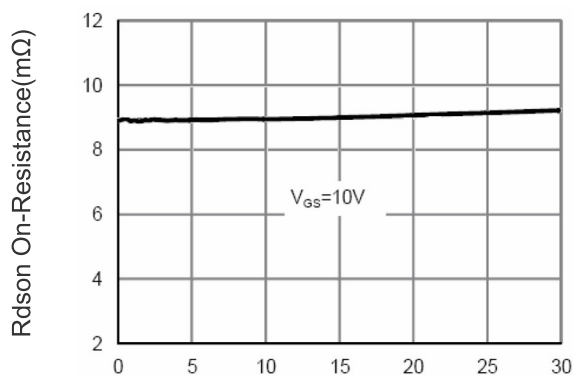
V_{GS} Gate-Source Voltage (V)

Figure 2 Transfer Characteristics



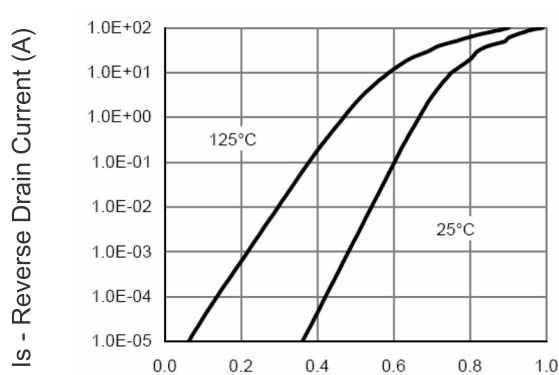
Q_g Gate Charge (nC)

Figure 5 Gate Charge



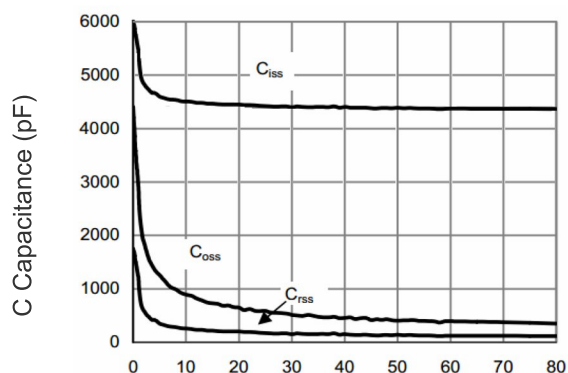
I_D - Drain Current (A)

Figure 3 Rdson- Drain Current

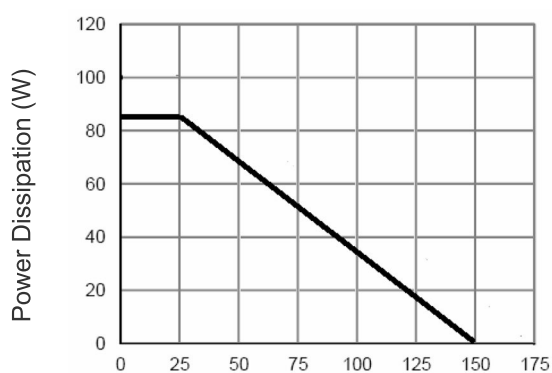


V_{SD} Source-Drain Voltage (V)

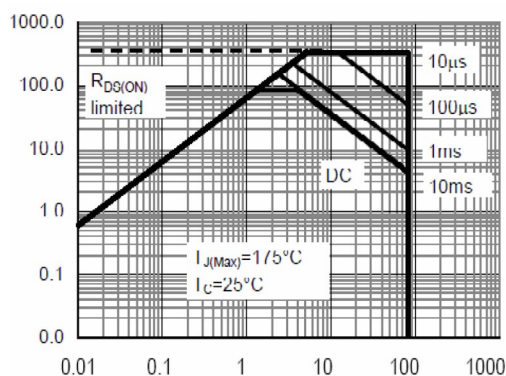
Figure 6 Source- Drain Diode Forward



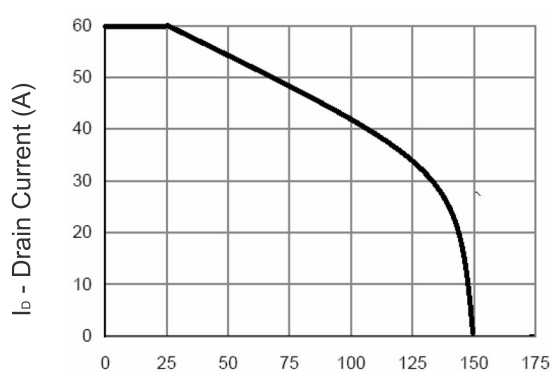
Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



TJ - Junction Temperature(°C)
Figure 9 Power De-rating



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



TJ - Junction Temperature(°C)
Figure 10 Id Current De-rating

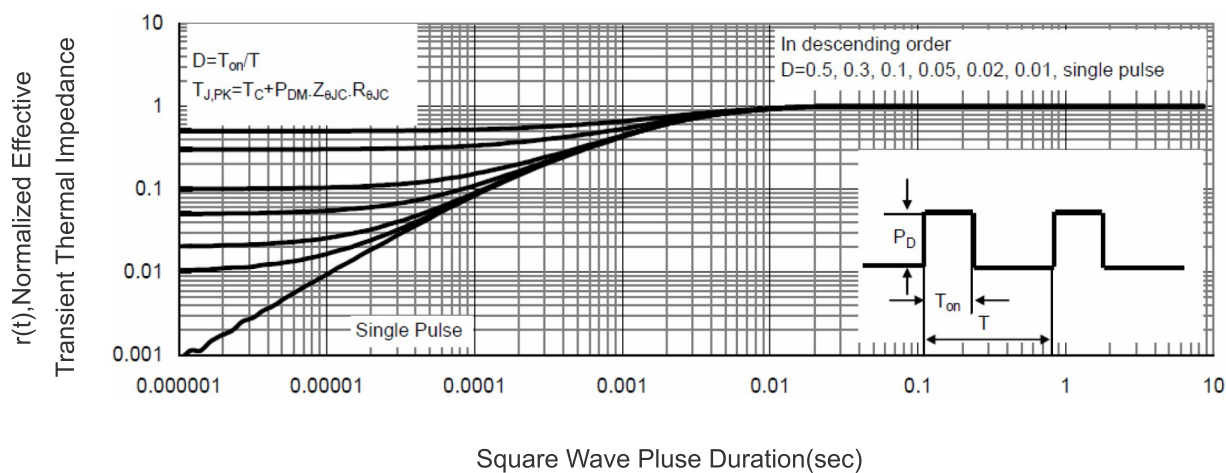
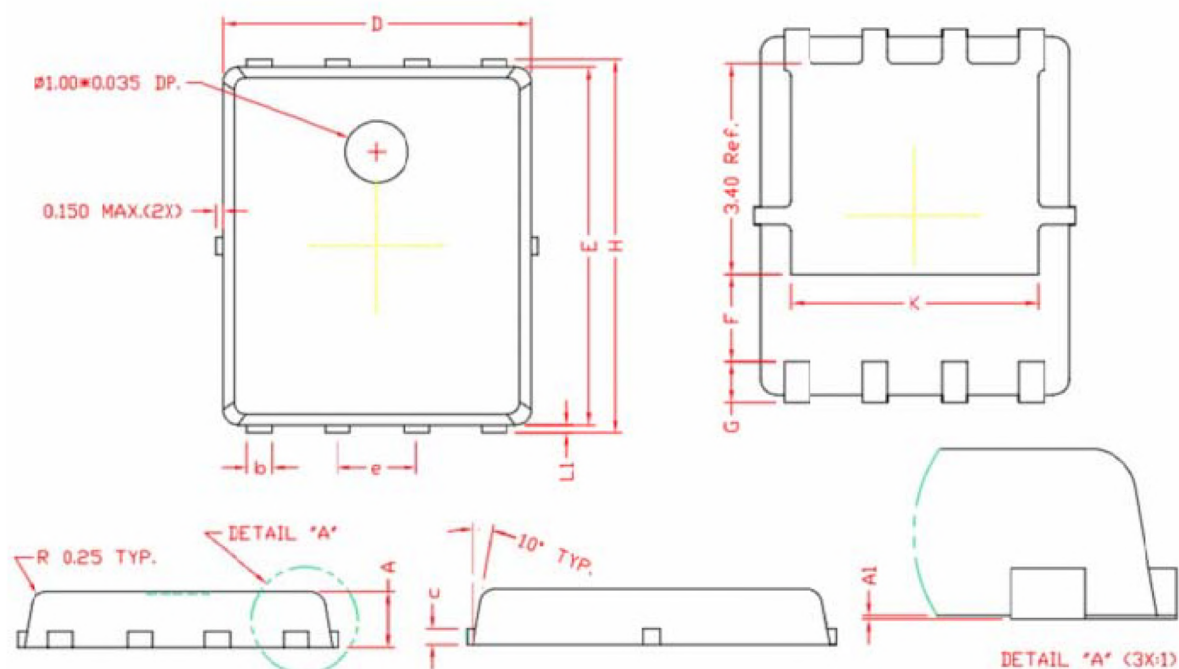


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252-2L Package Information



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
b	0.35	0.42	0.49
c	0.254 REF.		
D	4.90	5.00	5.10
F	1.40 REF.		
E	5.70	5.80	5.90
e	1.27 BSC.		
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G	0.60 REF.		
K	4.00 REF.		

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